

METHOD AND STRUCTURE FOR HEAT SINK ATTACHMENT IN SEMICONDUCTOR DEVICE PACKAGING

Abstract

A heat sink attachment structure includes an integrated circuit chip mounted on a substrate surface, and a thermal interface layer in contact with the integrated circuit chip. A heat sink is in contact with the thermal interface layer, and at least one spacer member is in contact between the substrate surface and the heat sink, wherein the at least one spacer member is provided with an adhesive material on top and bottom surfaces thereof.